

Single 2-Input AND Gate

MC74VHC1G08, MC74VHC1GT08

The MC74VHC1G08 / MC74VHC1GT08 is a single 2 input AND gate in tiny footprint packages. The MC74VHC1G08 has CMOS-level input thresholds while the MC74VHC1GT08 has TTL-level input thresholds.

The input structures provide protection when voltages up to 5.5 V are applied, regardless of the supply voltage. This allows the device to be used to interface 5 V circuits to 3 V circuits. Some output structures also provide protection when $V_{CC} = 0$ V and when the output voltage exceeds V_{CC} . These input and output structures help prevent device destruction caused by supply voltage – input/output voltage mismatch, battery backup, hot insertion, etc.

Features

- Designed for 2.0 V to 5.5 V V_{CC} Operation
- 3.5 ns t_{PD} at 5 V (typ)
- Inputs/Outputs Over-Voltage Tolerant up to 5.5 V
- I_{OFF} Supports Partial Power Down Protection
- Source/Sink 8 mA at 3.0 V
- Available in SC-88A, SC-74A, TSOP-5, SOT-953 and UDFN6 Packages
- Chip Complexity < 100 FETs
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

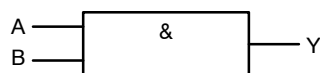


Figure 1. Logic Symbol

MARKING DIAGRAMS

	SC-88A DF SUFFIX CASE 419A	
	SC-74A DBV SUFFIX CASE 318BQ	
	TSOP-5 DT SUFFIX CASE 483	
	SOT-953 P5 SUFFIX CASE 527AE	
	UDFN6 1.2x1.0, 0.4P CASE 517AA-01	
	UDFN6 1.45 x 1.0 CASE 517AQ	
	UDFN6 1.0 x 1.0 CASE 517BX	

XX = Specific Device Code
M = Date Code*
A = Assembly Location
Y = Year
W = Work Week
▪ = Pb-Free Package

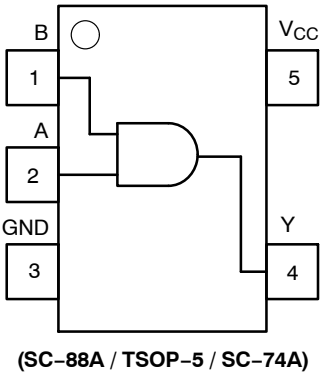
(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 8 of this data sheet.

MC74VHC1G08, MC74VHC1GT08

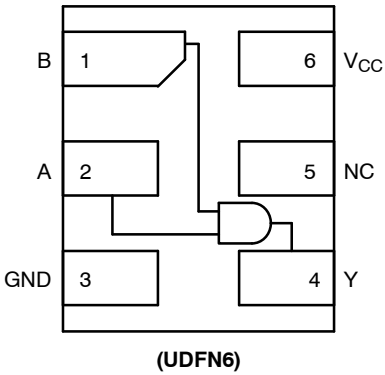


(SOT-953)

Figure 2. Pinout (Top View)

PIN ASSIGNMENT (SOT-953)

Pin	Function
1	A
2	GND
3	B
4	Y
5	V _{CC}



(UDFN6)

PIN ASSIGNMENT (UDFN)

Pin	Function
1	B
2	A
3	GND
4	Y
5	NC
6	V _{CC}

FUNCTION TABLE

Input		Output
A	B	Y
L	L	L
L	H	L
H	L	L
H	H	H

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MAXIMUM RATINGS

Symbol	Characteristics		Value	Unit
V_{CC}	DC Supply Voltage TSOP-5, SC-88A (NLV) SC-74A, SC-88A, UDFN6, SOT-553, SOT-953		-0.5 to +7.0 -0.5 to +6.5	V
V_{IN}	DC Input Voltage TSOP-5, SC-88A (NLV) SC-74A, SC-88A, UDFN6, SOT-553, SOT-953		-0.5 to +7.0 -0.5 to +6.5	V
V_{OUT}	DC Output Voltage (NLV)	1Gxx and MC74VHC1GT08P5T5G-L22088	-0.5 to $V_{CC} + 0.5$	V
		1GTxx Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode ($V_{CC} = 0$ V)	-0.5 to $V_{CC} + 0.5$ -0.5 to +7.0 -0.5 to +7.0	
	DC Output Voltage Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode ($V_{CC} = 0$ V)		-0.5 to $V_{CC} + 0.5$ -0.5 to +6.5 -0.5 to +6.5	V
I_{IK}	DC Input Diode Current $V_{IN} < GND$		-20	mA
I_{OK}	DC Output Diode Current (NLV)	1Gxx and MC74VHC1GT08P5T5G-L22088 $V_{OUT} > V_{CC}$, $V_{OUT} < GND$	± 20	mA
		1GTxx $V_{OUT} < GND$	-20	
	DC Output Diode Current $V_{OUT} < GND$		-20	mA
I_{OUT}	DC Output Source/Sink Current		± 25	mA
I_{CC} or I_{GND}	DC Supply Current per Supply Pin or Ground Pin		± 50	mA
T_{STG}	Storage Temperature Range		-65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 secs		260	°C
T_J	Junction Temperature Under Bias		+150	°C
θ_{JA}	Thermal Resistance (Note 2) SC-88A SC-74A SOT-553 SOT-953 UDFN6		377 320 324 254 154	°C/W
P_D	Power Dissipation in Still Air SC-88A SC-74A SOT-553 SOT-953 UDFN6		332 390 386 491 812	mW
MSL	Moisture Sensitivity		Level 1	-
F_R	Flammability Rating Oxygen Index: 28 to 34		UL 94 V-0 @ 0.125 in	-
V_{ESD}	ESD Withstand Voltage (Note 3) Human Body Model Charged Device Model		2000 1000	V
$I_{Latchup}$	Latchup Performance (Note 4)		± 100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Applicable to devices with outputs that may be tri-stated.
2. Measured with minimum pad spacing on an FR4 board, using 10mm-by-1inch, 2 ounce copper trace no air flow per JESD51-7.
3. HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to EIA/JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued per JEDEC/JEP172A.
4. Tested to EIA/JESD78 Class II.

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RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics		Min	Max	Unit
V _{CC}	Positive DC Supply Voltage		2.0	5.5	V
V _{IN}	DC Input Voltage		0	5.5	V
V _{OUT}	DC Output Voltage (NLV)	1Gxx and MC74VHC1GT08P5T5G–L22088	0	V _{CC}	V
		1GTxx Active–Mode (High or Low State)	0	V _{CC}	
		Tri–State Mode (Note 1)	0	5.5	
		Power–Down Mode (V _{CC} = 0 V)	0	5.5	
	DC Output Voltage		Active–Mode (High or Low State)	0	V _{CC}
		Tri–State Mode (Note 1)	0	5.5	
		Power–Down Mode (V _{CC} = 0 V)	0	5.5	
T _A	Operating Temperature Range		–55	+125	°C
t _r , t _f	Input Rise and Fall Time				

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS (MC74VHC1G08)

Symbol	Parameter	Test Conditions	V_{CC} (V)	$T_A = 25^\circ\text{C}$			$-40^\circ\text{C} \leq T_A \leq 85^\circ\text{C}$		$-55^\circ\text{C} \leq T_A \leq 125^\circ\text{C}$		Unit
				Min	Typ	Max	Min	Max	Min	Max	
V_{IH}	High-Level Input Voltage		2.0	1.5	–	–	1.5	–	1.5	–	V
			3.0	2.1	–	–	2.1	–	2.1	–	
			4.5	3.15	–	–	3.15	–	3.15	–	
			5.5	3.85	–	–	3.85	–	3.85	–	
V_{IL}	Low-Level Input Voltage		2.0	–	–	0.5	–	0.5	–	0.5	V
			3.0	–	–	0.9	–	0.9	–	0.9	
			4.5	–	–	1.35	–	1.35	–	1.35	
			5.5	–	–	1.65	–	1.65	–	1.65	
V_{OH}	High-Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL}	2.0	1.9	2.0	–	1.9	–	1.9	–	V
		$I_{OH} = -50 \mu\text{A}$	3.0	2.9	3.0	–	2.9	–	2.9	–	
		$I_{OH} = -50 \mu\text{A}$	4.5	4.4	4.5	–	4.4	–	4.4	–	
		$I_{OH} = -4 \text{ mA}$	3.0	2.58	–	–	2.48	–	2.34	–	
		$I_{OH} = -8 \text{ mA}$	4.5	3.94	–	–	3.80	–	3.66	–	
V_{OL}	Low-Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL}	2.0	–	0.0	0.1	–	0.1	–	0.1	V
		$I_{OL} = 50 \mu\text{A}$	3.0	–	0.0	0.1	–	0.1	–	0.1	
		$I_{OL} = 50 \mu\text{A}$	4.5	–	0.0	0.1	–	0.1	–	0.1	
		$I_{OL} = 4 \text{ mA}$	3.0	–	–	0.36	–	0.44	–	0.52	
		$I_{OL} = 8 \text{ mA}$	4.5	–	–	0.36	–	0.44	–	0.52	
I_{IN}	Input Leakage Current	$V_{IN} = 5.5$ V or GND	2.0 to 5.5	–	–	± 0.1	–	± 1.0	–	± 1.0	μA
I_{OFF}	Power Off Leakage Current (NLV)	$V_{IN} = 5.5$ V	0.0	–	–	1.0	–	10	–	10	μA
	Power Off Leakage Current	$V_{IN} = 5.5$ V or $V_{OUT} = 5.5$ V	0.0	–	–	1.0	–	10	–	10	μA
I_{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5	–	–	1.0	–	20	–	40	μA

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DC ELECTRICAL CHARACTERISTICS (MC74VHC1GT08)

Symbol	Parameter	Test Conditions	V _{CC} (V)	T _A = 25°C			-40°C ≤ T _A ≤ 85°C		-55°C ≤ T _A ≤ 125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
V _{IH}	High-Level Input Voltage		2.0	1.0	–	–	1.0	–	1.0	–	V
			3.0	1.4	–	–	1.4	–	1.4	–	
			4.5	2.0	–	–	2.0	–	2.0	–	
			5.5	2.0	–	–	2.0	–	2.0	–	
V _{IL}	Low-Level Input Voltage		2.0	–	–	0.28	–	0.28	–	0.28	V
			3.0	–	–	0.45	–	0.45	–	0.45	
			4.5	–	–	0.8	–	0.8	–	0.8	
			5.5	–	–	0.8	–	0.8	–	0.8	
V _{OH}	High-Level Output Voltage	V _{IN} = V _{IH} or V _{IL}	2.0	1.9	2.0	–	1.9	–	1.9	–	V
		I _{OH} = –50 μA	3.0	2.9	3.0	–	2.9	–	2.9	–	
		I _{OH} = –50 μA	4.5	4.4	4.5	–	4.4	–	4.4	–	
		I _{OH} = –4 mA	3.0	2.58	–	–	2.48	–	2.34	–	
		I _{OH} = –8 mA	4.5	3.94	–	–	3.80	–	3.66	–	
V _{OL}	Low-Level Output Voltage	V _{IN} = V _{IH} or V _{IL}	2.0	–	0.0	0.1	–	0.1	–	0.1	V
		I _{OL} = 50 μA	3.0	–	0.0	0.1	–	0.1	–	0.1	
		I _{OL} = 50 μA	4.5	–	0.0	0.1	–	0.1	–	0.1	
		I _{OL} = 4 mA	3.0	–	–	0.36	–	0.44	–	0.52	
		I _{OL} = 8 mA	4.5	–	–	0.36	–	0.44	–	0.52	
I _{IN}	Input Leakage Current	V _{IN} = 5.5 V or GND	2.0 to 5.5	–	–	±0.1	–	±1.0	–	±1.0	μA
I _{OFF}	Power Off Leakage Current	V _{IN} = 5.5 V or V _{OUT} = 5.5 V	0	–	–	1.0	–	10	–	10	μA
	Power Off Leakage Current (MC74VHC1GT08P 5T5G–L22088 Only)	V _{IN} = 5.5 V	0	–	–	1.0	–	10	–	10	
I _{CC}	Quiescent Supply Current	V _{IN} = V _{CC} or GND	5.5	–	–	1.0	–	20	–	40	μA
I _{CC} T	Increase in Quiescent Supply Current per Input Pin	One Input: V _{IN} = 3.4 V; Other Input at V _{CC} or GND	5.5	–	–	1.35	–	1.5	–	1.65	mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = 25°C			-40°C ≤ T _A ≤ 85°C		-55°C ≤ T _A ≤ 125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t _{PLH} , t _{PHL}	Propagation Delay, A to Y (Figures 3 and 4)	C _L = 15 pF	3.0 to 3.6	–	4.1	8.8	–	10.5	–	12.5	ns
		C _L = 50 pF		–	5.9	12.3	–	14.0	–	16.5	
		C _L = 15 pF	4.5 to 5.5	–	3.5	5.9	–	7.0	–	9.0	
		C _L = 50 pF		–	4.2	7.9	–	9.0	–	11.0	
C _{IN}	Input Capacitance			–	4.0	10	–	10	–	10	pF
C _{OUT}	Output Capacitance	Output in High Impedance State		–	6.0	–	–	–	–	–	pF

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AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Typical @ 25°C, V _{CC} = 5.0 V	Unit
C _{PD}	Power Dissipation Capacitance (Note 5)	8.0	pF

5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \cdot V_{CC} \cdot f_{in} + I_{CC}$. C_{PD} is used to determine the no-load dynamic power consumption; $P_D = C_{PD} \cdot V_{CC}^2 \cdot f_{in} + I_{CC} \cdot V_{CC}$.

MC74VHC1G08, MC74VHC1GT08

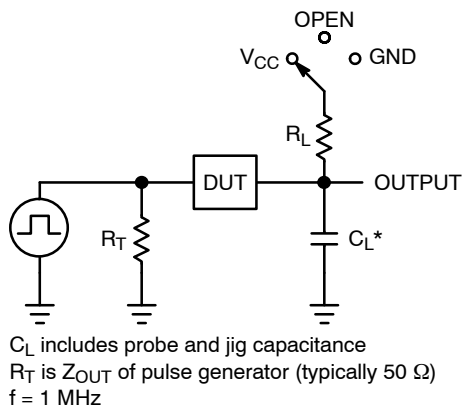


Figure 3. Test Circuit

Test	Switch Position	C_L , pF	R_L , Ω
t_{PLH} / t_{PHL}	Open	See AC Characteristics Table	X
t_{PLZ} / t_{PZL}	V_{CC}		1 k
t_{PHZ} / t_{PZH}	GND		1 k

X = Don't Care

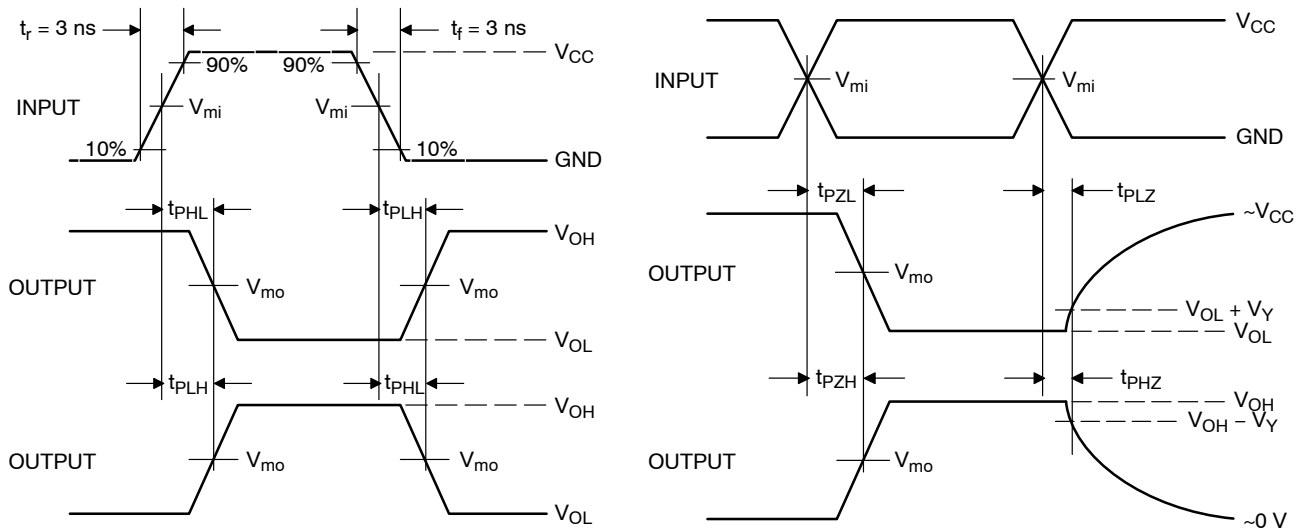


Figure 4. Switching Waveforms

V_{CC} , V	V_{mi} , V	V_{mo} , V		V_Y , V
		t_{PLH} , t_{PHL}	t_{PLZ} , t_{PZL} , t_{PZH} , t_{PHZ}	
3.0 to 3.6	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.3
4.5 to 5.5	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.3

MC74VHC1G08, MC74VHC1GT08

ORDERING INFORMATION

Device	Packages	Specific Device Code	Pin 1 Orientation (See below)	Shipping [†]
MC74VHC1G08DFT1G	SC-88A	V2	Q2	3000 / Tape & Reel
MC74VHC1G08DFT1G-L22038**	SC-88A	V2	Q2	3000 / Tape & Reel
MC74VHC1G08DFT2G	SC-88A	V2	Q4	3000 / Tape & Reel
MC74VHC1G08DFT2G-F22038**	SC-88A	V2	Q4	3000 / Tape & Reel
NLVVHC1G08DFT1G*	SC-88A	V2	Q2	3000 / Tape & Reel
NLVVHC1G08DFT2G*	SC-88A	V2	Q4	3000 / Tape & Reel
M74VHC1GT08DFT1G	SC-88A	VT	Q2	3000 / Tape & Reel
M74VHC1GT08DFT1G-L22038**	SC-88A	VT	Q2	3000 / Tape & Reel
M74VHC1GT08DFT2G	SC-88A	VT	Q4	3000 / Tape & Reel
M74VHC1GT08DFT2G-F22038**	SC-88A	VT	Q4	3000 / Tape & Reel
NLVVHC1GT08DFT1G*	SC-88A	VT	Q2	3000 / Tape & Reel
NLVVHC1GT08DFT2G*	SC-88A	VT	Q4	3000 / Tape & Reel
MC74VHC1G08DBVT1G	SC-74A	V2	Q4	3000 / Tape & Reel
MC74VHC1GT08DBVT1G	SC-74A	VT	Q4	3000 / Tape & Reel
MC74VHC1G08DTT1G**	TSOP-5	V2	Q4	3000 / Tape & Reel
M74VHC1GT08DTT1G**	TSOP-5	VT	Q4	3000 / Tape & Reel
NLV74VHC1G08DTT1G*	TSOP-5	V2	Q4	3000 / Tape & Reel
NLVVHC1GT08DTT1G*	TSOP-5	VT	Q4	3000 / Tape & Reel
MC74VHC1G08P5T5G	SOT-953	E	Q2	8000 / Tape & Reel
MC74VHC1G08P5T5G-L22088**	SOT-953	E	Q2	8000 / Tape & Reel
MC74VHC1GT08P5T5G	SOT-953	P	Q2	8000 / Tape & Reel
MC74VHC1GT08P5T5G-L22088**	SOT-953	P	Q2	8000 / Tape & Reel
MC74VHC1G08MU1TCG	UDFN6, 1.45 x 1.0, 0.5P	K (Rotated 180° CW)	Q4	3000 / Tape & Reel
MC74VHC1GT08MU1TCG	UDFN6, 1.45 x 1.0, 0.5P	4 (Rotated 270° CW)	Q4	3000 / Tape & Reel
MC74VHC1G08MU2TCG	UDFN6, 1.2 x 1.0, 0.4P	2	Q4	3000 / Tape & Reel
MC74VHC1G08MU3TCG	UDFN6, 1.0 x 1.0, 0.35	D (Rotated 270° CW)	Q4	3000 / Tape & Reel
MC74VHC1GT08MU3TCG	UDFN6, 1.0 x 1.0, 0.35	K	Q4	3000 / Tape & Reel

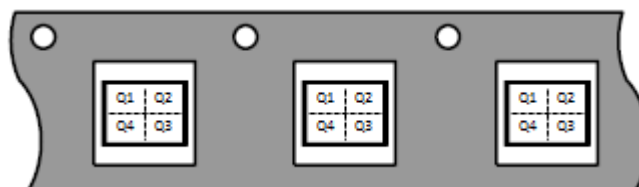
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

**Please refer to NLV specifications for this device.

PIN 1 ORIENTATION IN TAPE AND REEL

Direction of Feed

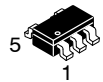


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

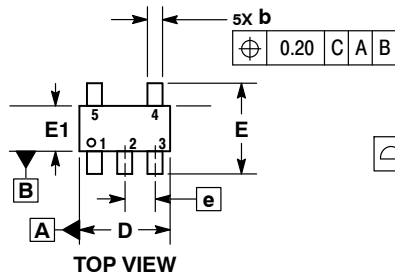
ON



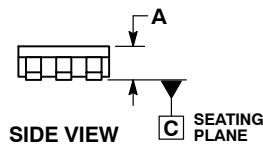
SCALE 2:1

SC-74A CASE 318BQ ISSUE B

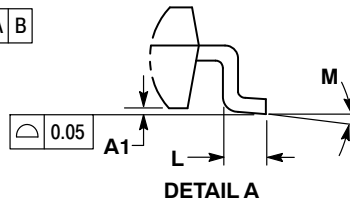
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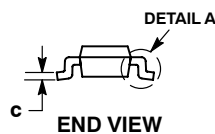
TOP VIEW



SIDE VIEW



DETAIL A



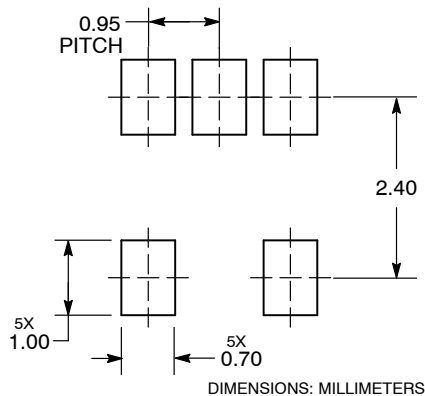
END VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

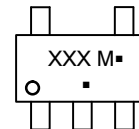
MILLIMETERS		
DIM	MIN	MAX
A	0.90	1.10
A1	0.01	0.10
b	0.25	0.50
c	0.10	0.26
D	2.85	3.15
E	2.50	3.00
E1	1.35	1.65
e	0.95 BSC	
L	0.20	0.60
M	0°	10°

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER: 98AON66279G

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DESCRIPTION: SC-74A

PAGE 1 OF 1

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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

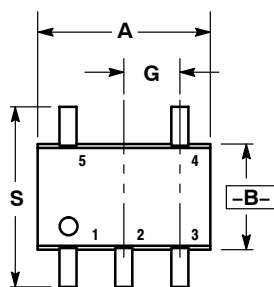
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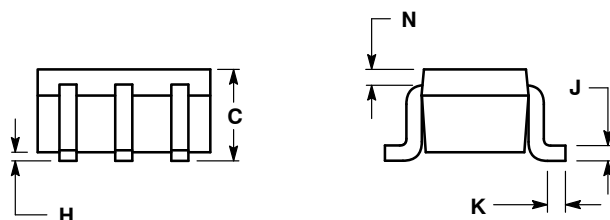
SCALE 2:1

SC-88A (SC-70-5/SOT-353)
CASE 419A-02
ISSUE L

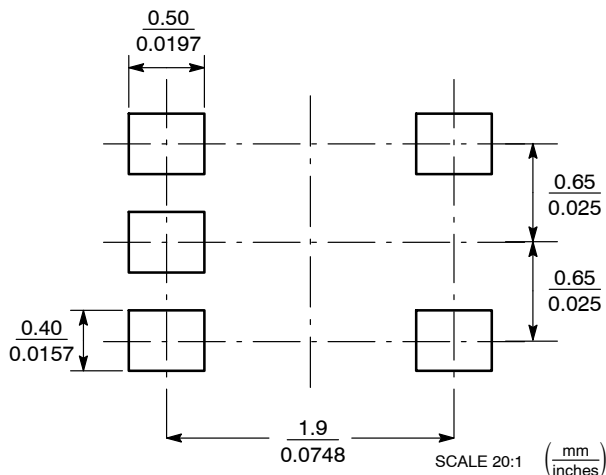
DATE 17 JAN 2013



D 5 PL $\oplus$ 0.2 (0.008) (M) B (M)



SOLDER FOOTPRINT



STYLE 1:

- PIN 1. BASE
- 2. EMITTER
- 3. BASE
- 4. COLLECTOR
- 5. COLLECTOR

STYLE 2:

- PIN 1. ANODE
- 2. EMITTER
- 3. BASE
- 4. COLLECTOR
- 5. CATHODE

STYLE 3:

- PIN 1. ANODE 1
- 2. N/C
- 3. ANODE 2
- 4. CATHODE 2
- 5. CATHODE 1

STYLE 4:

- PIN 1. SOURCE 1
- 2. DRAIN 1/2
- 3. SOURCE 1
- 4. GATE 1
- 5. GATE 2

STYLE 5:

- PIN 1. CATHODE
- 2. COMMON ANODE
- 3. CATHODE 2
- 4. CATHODE 3
- 5. CATHODE 4

STYLE 6:

- PIN 1. EMITTER 2
- 2. BASE 2
- 3. EMITTER 1
- 4. COLLECTOR
- 5. COLLECTOR 2/BASE 1

STYLE 7:

- PIN 1. BASE
- 2. EMITTER
- 3. BASE
- 4. COLLECTOR
- 5. COLLECTOR

STYLE 8:

- PIN 1. CATHODE
- 2. COLLECTOR
- 3. N/C
- 4. BASE
- 5. EMITTER

STYLE 9:

- PIN 1. ANODE
- 2. CATHODE
- 3. ANODE
- 4. ANODE
- 5. ANODE

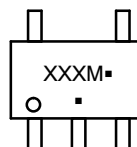
Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.071	0.087	1.80	2.20
B	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026 BSC		0.65 BSC	
H	---	0.004	---	0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

M = Date Code

▪ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER: 98ASB42984B

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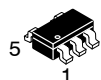
DESCRIPTION: SC-88A (SC-70-5/SOT-353)

PAGE 1 OF 1

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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

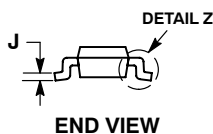
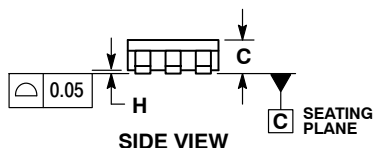
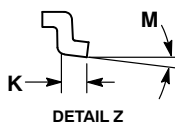
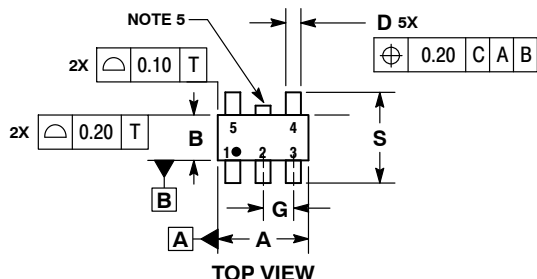
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SCALE 2:1

TSOP-5 CASE 483 ISSUE N

DATE 12 AUG 2020

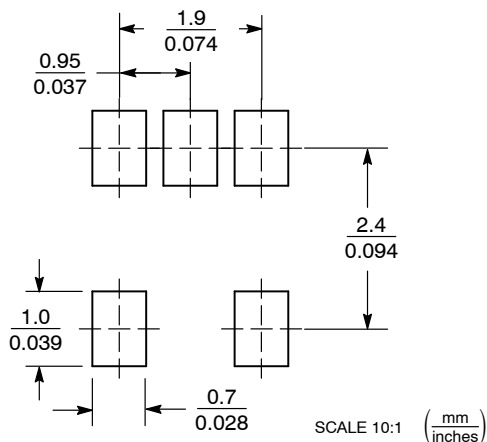


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION A.
5. OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

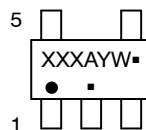
DIM	MILLIMETERS	
	MIN	MAX
A	2.85	3.15
B	1.35	1.65
C	0.90	1.10
D	0.25	0.50
G	0.95 BSC	
H	0.01	0.10
J	0.10	0.26
K	0.20	0.60
M	0°	10°
S	2.50	3.00

SOLDERING FOOTPRINT*

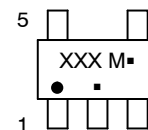


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



Analog



Discrete/Logic

XXX = Specific Device Code
 A = Assembly Location
 Y = Year
 W = Work Week
 ■ = Pb-Free Package

XXX = Specific Device Code
 M = Date Code
 ■ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

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DESCRIPTION: TSOP-5

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MECHANICAL CASE OUTLINE

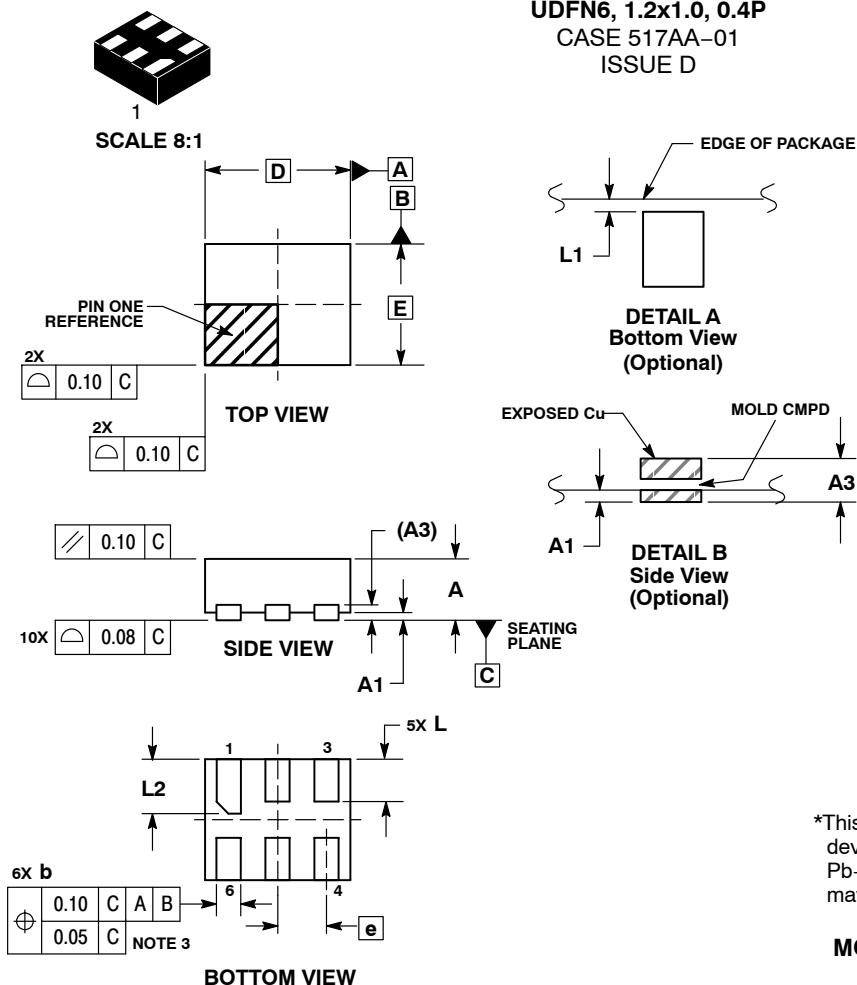
PACKAGE DIMENSIONS

ON Semiconductor®



UDFN6, 1.2x1.0, 0.4P
CASE 517AA-01
ISSUE D

DATE 03 SEP 2010



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.127 REF	
b	0.15	0.25
D	1.20 BSC	
E	1.00 BSC	
e	0.40 BSC	
L	0.30	0.40
L1	0.00	0.15
L2	0.40	0.50

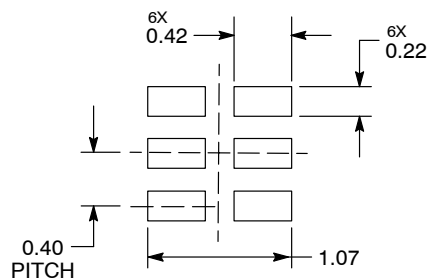
GENERIC MARKING DIAGRAM*



X = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	6 PIN UDFN, 1.2X1.0, 0.4P	PAGE 1 OF 1

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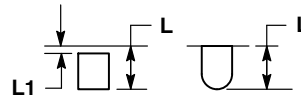
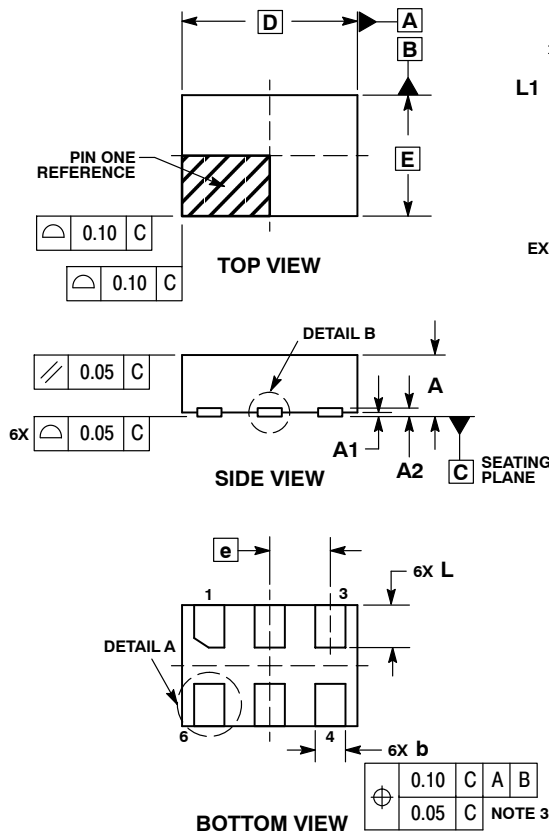
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



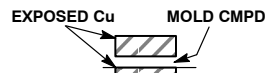
SCALE 4:1

UDFN6, 1.45x1.0, 0.5P
CASE 517AQ
ISSUE O

DATE 15 MAY 2008



DETAIL A
OPTIONAL
CONSTRUCTIONS



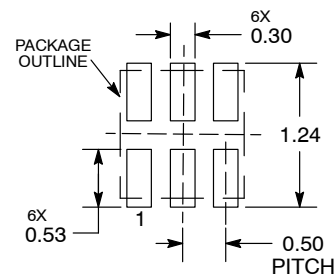
DETAIL B
OPTIONAL
CONSTRUCTIONS

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A2	0.07	REF
b	0.20	0.30
D	1.45	BSC
E	1.00	BSC
e	0.50	BSC
L	0.30	0.40
L1	—	0.15

MOUNTING FOOTPRINT



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



X = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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DESCRIPTION:	UDFN6, 1.45x1.0, 0.5P	PAGE 1 OF 1

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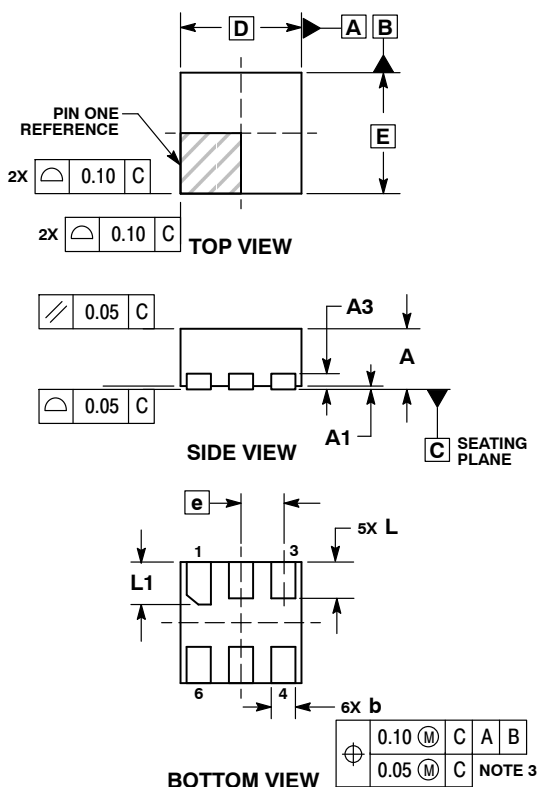
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 4:1

UDFN6, 1x1, 0.35P
CASE 517BX
ISSUE O

DATE 18 MAY 2011

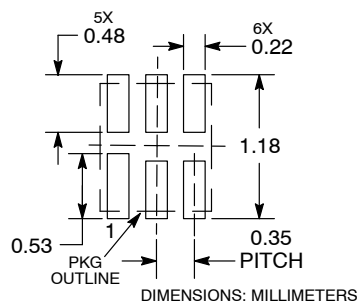


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

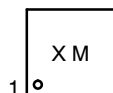
MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13	REF
b	0.12	0.22
D	1.00	BSC
E	1.00	BSC
e	0.35	BSC
L	0.25	0.35
L1	0.30	0.40

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



X = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

ON



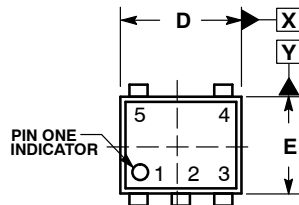
SCALE 4:1

SOT-953

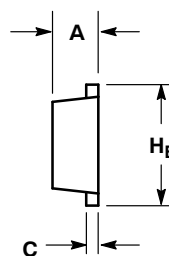
CASE 527AE

ISSUE E

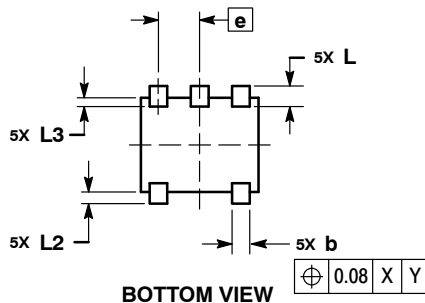
DATE 02 AUG 2011



TOP VIEW

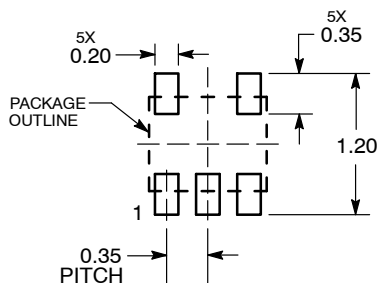


SIDE VIEW



BOTTOM VIEW

SOLDERING FOOTPRINT*



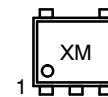
DIMENSIONS: MILLIMETERS

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.34	0.37	0.40
b	0.10	0.15	0.20
C	0.07	0.12	0.17
D	0.95	1.00	1.05
E	0.75	0.80	0.85
e	0.35 BSC		
H _E	0.95	1.00	1.05
L	0.175 REF		
L2	0.05	0.10	0.15
L3			0.15

GENERIC MARKING DIAGRAM*



X = Specific Device Code
M = Month Code

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot "▪", may or may not be present.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	SOT-953	PAGE 1 OF 1

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